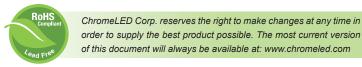


2. Tolerance is  $\pm$  0.25mm (0.01") unless otherwise noted. 3. Specifications are subject to change without notice.

# SPECIFICATIONS CSD131IR850C

## **OUTLINES DIMENSIONS** 3.20 [0.13"] Ø1.80 [Ø0.07″] 2.00 [0.08"] Ø0.40 [Ø0.02"] .40 [0,09"] 2,40 [0,09"] Cathode Mark 2.0 [0.08"] RECOMMEND PAD LAYOUT ITEM **MATERIALS** Resin (mold) Ероху Lens color Water transparent 0.50 [0.02"] 0.50 [0.02"] Dice AlGaAs/AlGaAs Notes: Emitted color Infrared 1. All Dimensions are in millimeters (inches).

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CSD131IR850C	GaAlAs/GaAs	Infrared	Water Clear	15°





### **ABSOLUTE MAXIMUM RATINGS**

(TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	Po	180	mW
Pulse Current Forward Current	lfp	1	А
Continuous Forward Current	lF	100	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-40~+85	°C
Storage Temperature Range	Тѕтс	-40~+100	°C

IFP = Pulse Width  $\leq$  10 ms, Duty Ratio  $\leq$ 1/10. Soldering Condition: 260 °C/ 5sec

### **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

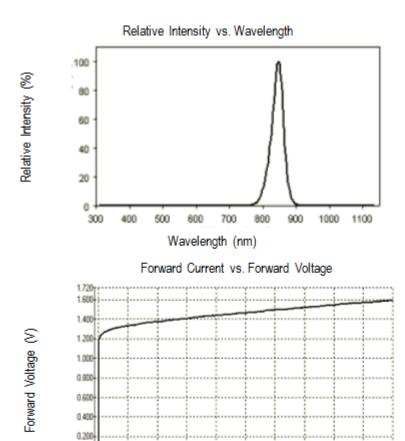
Parameter	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Radiant Intensity	le	I⊧ = 100mA	21.1	23	ı	mW/sr
Forward Voltage	VF	I <sub>F</sub> = 100mA	-	1.5	1.8	V
Viewing Angle	201/2	I <sub>F</sub> = 100mA	-	15	-	deg
Peak Wavelength	<b>λ</b> P	I⊧ = 100mA	-	850	-	nm
Spectral Line half-width	Δλ	I <sub>F</sub> = 100mA	-	42	-	nm



<sup>\*</sup>Tolerance of viewing angle: -10 / +5 deg.



## **OPTICAL CHARACTERISTIC CURVES**

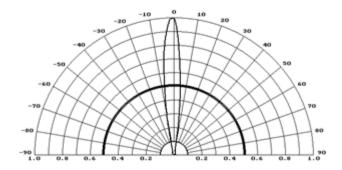


Directive Characteristics

Forward Current (mA)

10.00

20.00





ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



#### **SOLDERING CONDITIONS – LAMP TYPE LED**

- \* Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- \* Recommended soldering conditions

Dip Soldering				
Pre-Heat	100 °C Max			
Pre-Heat Time	60 Second Max			
Solder Bath Temperature	260 °C Max			
Dippng Time	5 Second Max			
Dipping Position	No lower than 3mm from the base of the epoxy			

Hand Soldering					
Temperature Soldering Time Position	3mm Series	Others			
	300 °C Max	350 °C Max			
	3 Second Max	3 Second Max			
	No closer than 3mm from the	No closer than 3mm from the			
	base of the epoxy	base of the epoxy			

- \* Do not apply any stress to the lead. Particularly when heated.
- \* The LED must not be repositioned after soldering.
- \* After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- \* Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- \* When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- \* Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

